

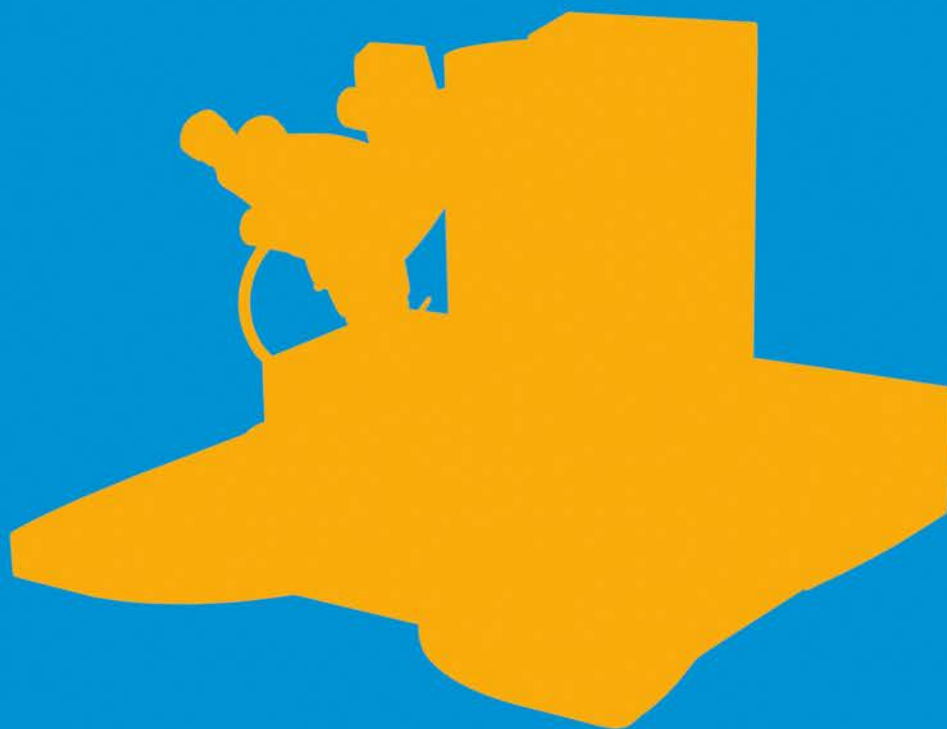
25 Years

Made in Germany

Installed in over 60 Countries



tpt



HB75 Die Bonder

Stamping Dispensing Placing

# HB75 Semi-Automatic Die Bonder

with motorized Z-Axis



## Epoxy Dispensing or Stamping

Fast and precise epoxy application



## Easy Control With 6,5" Touch Panel

Access & storage of all parameters, 100 set capacity



## Automatic Bond Height Adjustment

Z-axis sensor identifies touch down & sets height parameters



## Pick & Place with integrated vacuum pump

Pick up microchip from die-carrier and place it on substrate



## Rotatable Head

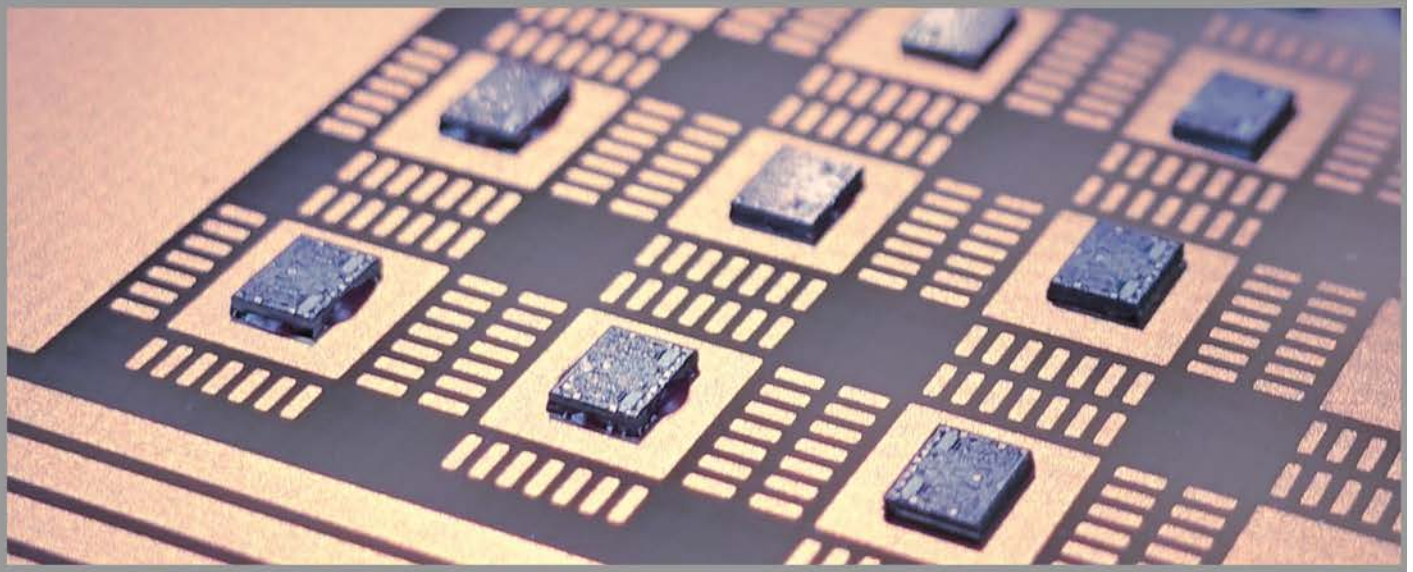
Quick exchange between different tools and epoxy



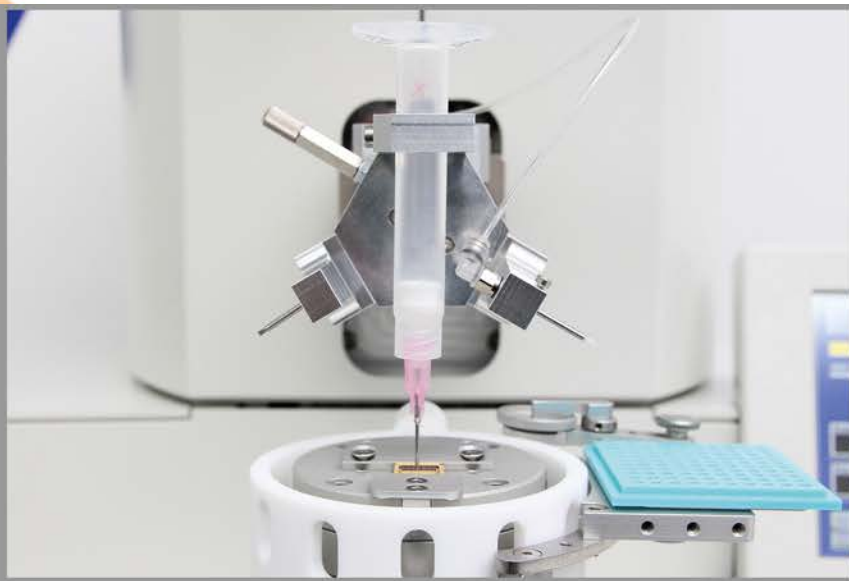
## Angle Alignment

Microchip angle alignment due to the rotatable base plate

# Ideal for laboratories and pilot production lines



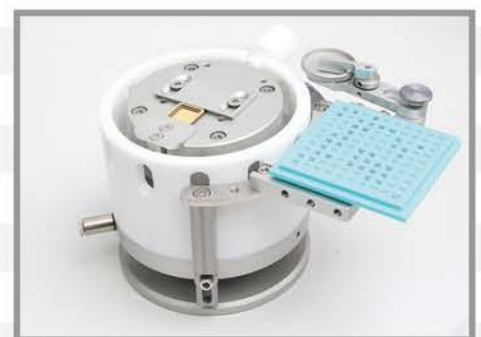
Chips placed with HB75



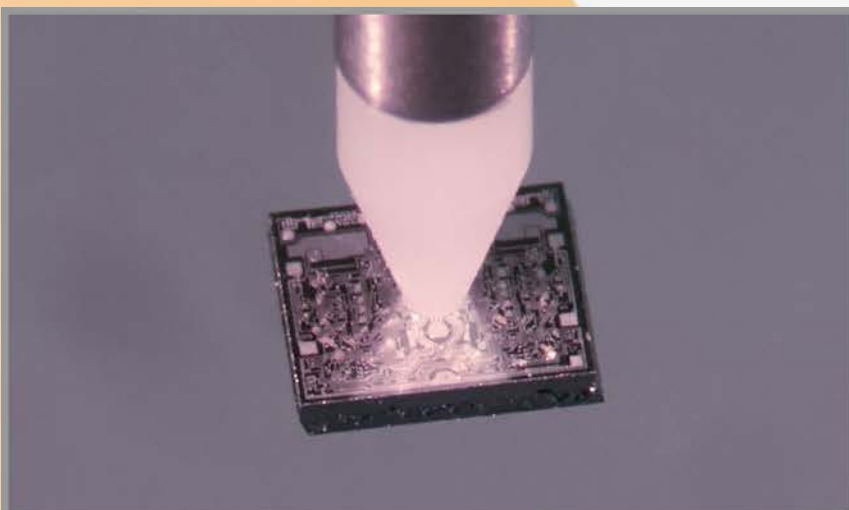
Rotatable Head



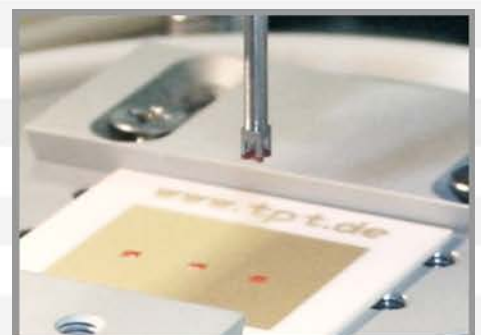
built in Vacuum Pump



Stage with Waffle Pack Holder



Delrin Tip

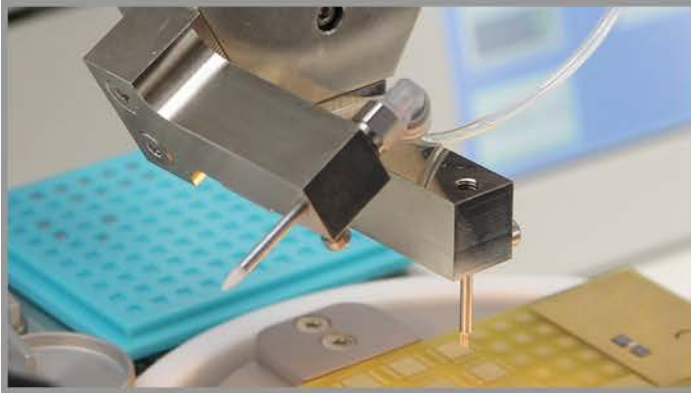


Stamping



# HB75 Semi-Automatic Die Bonder

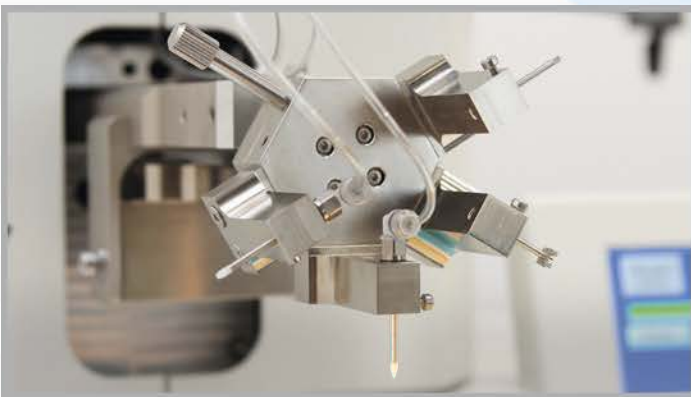
## Head Configurations



Two tools on rotatable bond head

### Configuration 01

- 1 x Stamping Tool
- 1 x Pickup Tool



Four tools on rotatable bond head

### Configuration 02

- 2 x Stamping Tool
- 2 x Pickup Tool



Pickup Tool turnable with Motor

### Configuration 03

- 1 x Stamping Tool
- 1 x Pickup Tool turnable



Epoxy Dispenser

### Dispenser Kit

- 1 x Stamping Tool
- 1 x Pickup Tool rotatable
- Epoxy Dispenser Kit

# TPT Heater Stages and Accessories

## Heater Stages



Ø 60mm



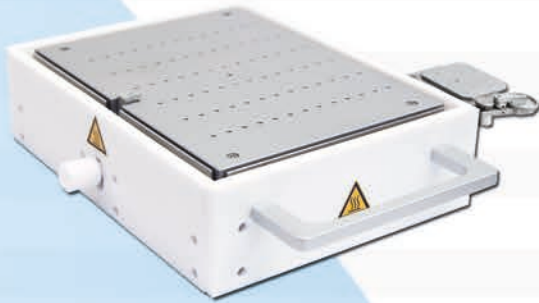
Ø 90mm



100mm x 100mm



100mm x 150mm



150mm x 200mm



Advanced Epoxy Table with  
Fine Adjustment

## Accessories



Dispenser Kit



Manual-Z



Dynamic Search Box



Wire Bonder	<b>HB05</b>	<b>HB10</b>	<b>HB16</b>	<b>HB30</b>	<b>HB100</b>
Bonding Method	<b>Wedge &amp; Ball</b>	Wedge & Ball	Wedge & Ball	Wedge	Wedge & Ball
Wire Size	<b>17-75µm</b>	17-75µm	17-75µm	<b>100-500µm</b>	17-75µm
Ribbon max.	<b>25x250µm</b>	25x250µm	25x250µm	<b>300x2000µm</b>	25x250µm
Type	<b>Manual</b>	Semi-Automatic	Semi-Automatic	<b>Semi-Automatic</b>	Automatic
Motorized Axis	-	Z-Axis	Z- & Y-Axes	<b>Z- &amp; Y-Axes</b>	X- Y- Z- & R - Axes
Auto Height Setup	-	Yes	Yes	Yes	Yes
Loop Height Control	-	Yes	Yes	Yes	Yes
Loop Length Control	-	-	Yes	Yes	Yes
Pattern Function	-	-	-	-	Yes
Control Panel	<b>4" TFT</b>	6,5" Touch Screen	6,5" Touch Screen	<b>6,5" Touch Screen</b>	21" Touch Screen
X-Y Manipulator Ratio	<b>6:1</b>	6:1	6:1	<b>6:1</b>	Joystick
Program Storage	<b>20</b>	100	100	<b>100</b>	100
Ultrasonic Power	<b>10 Watt</b>	10 Watt	10 Watt	<b>50 Watt</b>	10 Watt
max. Bond Force	<b>200 cN</b>	150 cN	150 cN	<b>1800 cN</b>	150 cN
Bond Time	<b>0-1 sec.</b>	0-10 sec.	0-10 sec.	<b>0-10 sec.</b>	0-10 sec.
Ultrasonic System	<b>63,3 kHz</b>	63,3 kHz	63,3 kHz	<b>60 kHz</b>	63,3 kHz
Various Frq. available	-	Yes	Yes	-	Yes
Wire Clamp	<b>motorized</b>	motorized	motorized	-	motorized
Wire Termination	<b>clamp</b>	clamp	clamp / table tear	<b>wire cutting</b>	clamp / table tear
Dimensions (LxWxH)	<b>550x450x250mm</b>	680x640x500mm	680x640x500mm	<b>680x640x570mm</b>	620x750x680mm
Weight	<b>29kg</b>	42kg	42kg	<b>50kg</b>	72kg
Electrical Requirements	<b>100-240 V / 6A max.</b>	100-240V / 6A max	100-240V / 6A max.	<b>100-240V / 6A max.</b>	100-240V / 6A max.
Industry Standard	<b>CE</b>	CE	CE	<b>CE</b>	CE
Pick & Place Option	<b>Yes</b>	Yes	Yes	<b>Yes</b>	-
Video Target Option	<b>Yes</b>	Yes	Yes	<b>Yes</b>	-
Pull Tester Option	<b>Yes</b>	Yes	Yes	-	-
Copper Bonding Option	-	Yes	Yes	-	-
Extended Force Option	-	Yes	Yes	-	Yes

Die Bonder	<b>HB75</b>
Die Size max.	<b>10x10mm</b>
Placement View	<b>Microscope</b>
Type	<b>Semi-Automatic</b>
Motorized Axis	<b>Z-Axis</b>
Control Panel	<b>6,5" Touch Screen</b>
Bond Force Control	<b>Programmable</b>
max. Bond Force	<b>150 cN</b>
Vacuum Pump	<b>Built-in</b>
X-Y Manipulator Ratio	<b>6:1</b>
Fine Adjustment Screws	-
Adjustable View Angle	-
Rotatable Table	<b>Yes</b>
Epoxy Dispensing Option	<b>Yes</b>
Heater Stage Control	<b>Yes</b>
Bond Time Control	<b>Yes</b>
Auto Height Setup	<b>Yes</b>
Program Storage	<b>Yes</b>
Rotatable Head	<b>Yes</b>
Video Target Option	<b>Yes</b>
Extended Force Option	<b>Yes</b>
Dimensions (LxWxH)	<b>680x640x500mm</b>
Weight	<b>42kg</b>
Electrical Requirements	<b>100-240V / 6A max</b>
Industry Standard	<b>CE</b>

Specifications are subject to change without prior notice

# Wire & Die Bonder “Made in Germany”

Relying on over **25 years** of wire bonding know-how,

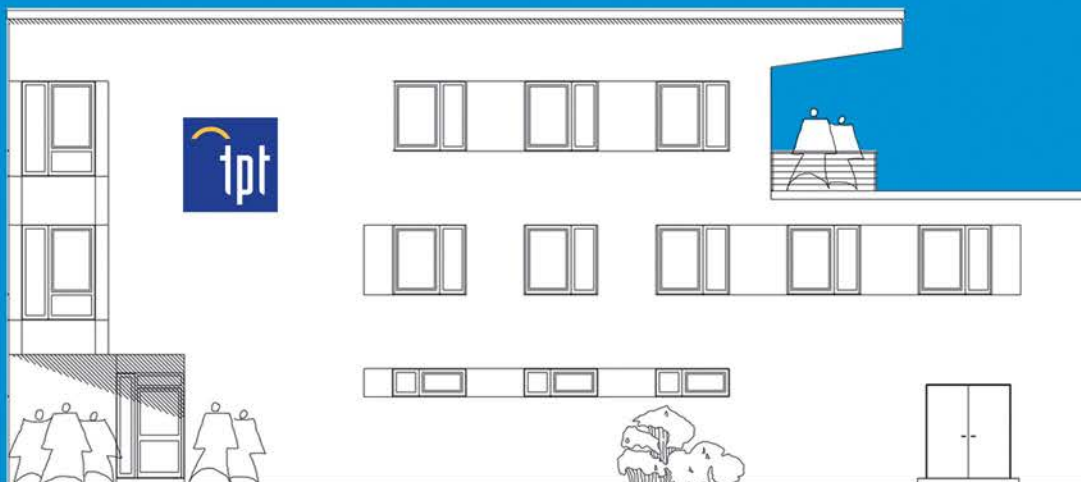
TPT designs and manufactures a wide range of manual and automatic wire bonding machines.

TPT is a privately owned company, with the goal to provide the **highest quality** wire bonding equipment.

**Based in Munich**, TPT draws strength from Germany's high technology region.

TPT bonders are used in many leading **Universities, Institutes and Semiconductor,**

**Aerospace and Medical** device companies throughout the world.



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